This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1.   (previously presented) A multi-package module comprising stacked first and second packages, each said package including a die attached to a substrate, wherein the second package is inverted, wherein the second and first substrates are interconnected by wire bonding, and wherein at least one said package comprises a stacked die package.

2.   (previously presented) The multi-package module of claim 1 wherein the first package comprises a stacked die package.

3.   (previously presented) The multi-package module of claim 1 wherein each of the first package and the second package comprises a stacked die package.

4.   (previously presented) The multi-package module of claim 1 wherein the second package comprises a stacked die package.

5.   (original) The multi-package module of claim 1 wherein adjacent stacked die in the stacked die package are separated by a spacer.

6.   (original) The multi-package module of claim 1, further comprising a heat spreader over the second package.

7.   (original) The multi-package module of claim 1, further comprising an additional package stacked over the inverted second package.

8.   (original) The multi-package module of claim 7 wherein the additional package is a land grid array package.

9.   (original) The multi-package module of claim 7 wherein the additional package is an inverted land grid array package.

10.   (original) The multi-package module of claim 7 wherein the additional package is a ball grid array package.

11.   (original) The multi-package module of claim 7 wherein the additional package is a flip chip package.

12 - 20. (canceled)

21.   (currently amended) A mobile device comprising the multi-package module of claim 1, said multi-package module being connected to underlying circuitry in the device.

22.   (currently amended) A computer comprising the multi-package module of claim 1, said multi-package module being connected to underlying circuitry in the computer.